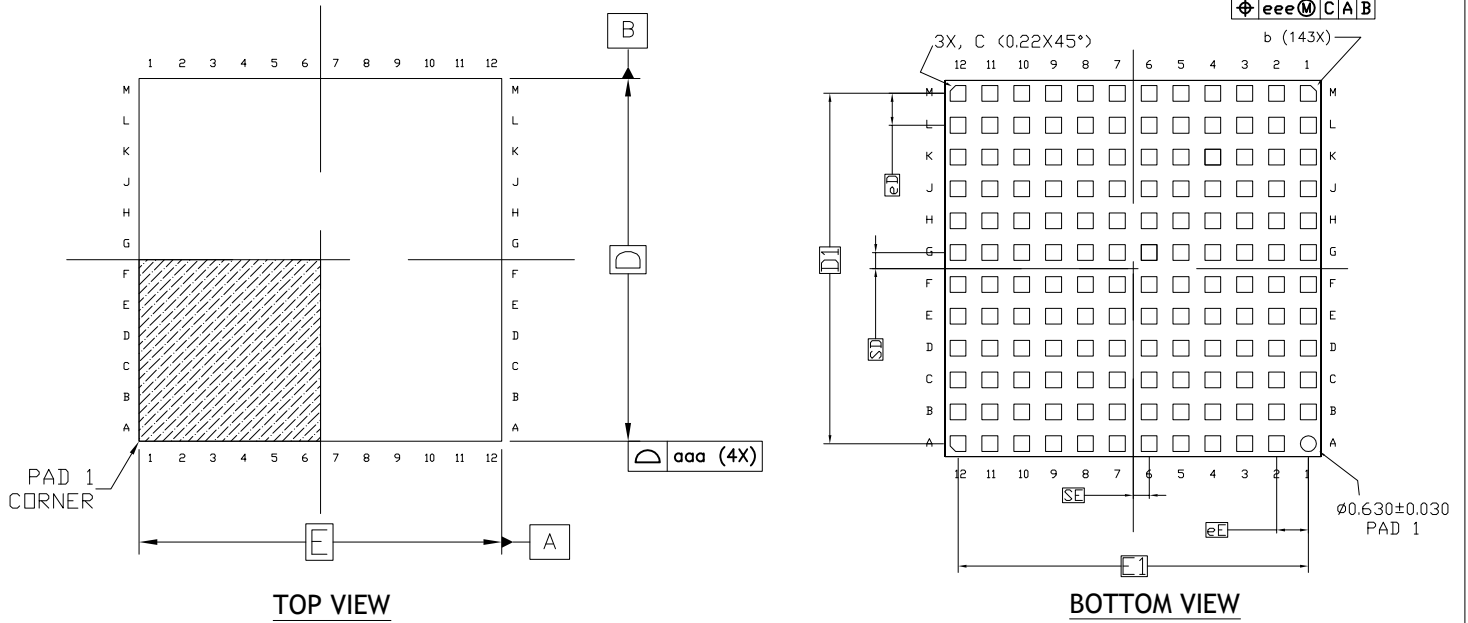


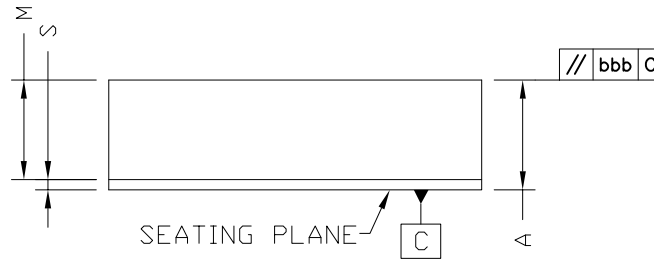
Revision History

REV.	Description	Date	APP'D
A	DRAWING ORIGATION	SEPT/15/2016	ECN 1650-03 12/06/2016 jh
A.1	CORRECT TYPO (AREA -> ARE)	JAN/26/2018	ECN 1805-05 01/30/2018 jh



TOP VIEW

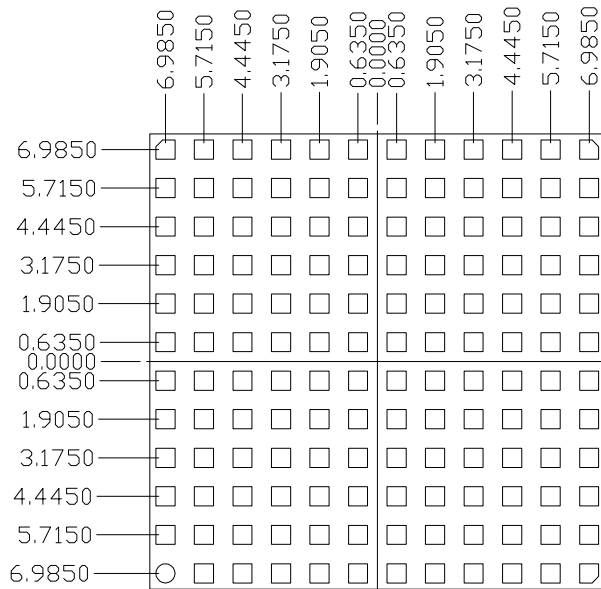
BOTTOM VIEW



SIDE VIEW

	Symbol	Common Dimensions
Package :		SiPLGA
Body Size:	X	E 15.000
	Y	D 15.000
LGA Pad Pitch :	X	eE 1.270
	Y	eD 1.270
Total Thickness :	A	2.820±0.10
Mold Thickness :	M	2.500±0.05
Substrate Thickness :	S	0.320±0.04
LGA Pad Size :	b	SQ 0.630±0.030
Stand Off :	A1	N/A
Ball Width :		N/A
Package Edge Tolerance :	aaa	0.150
Mold Flatness :	bbb	0.100
Coplanarity:	ddd	N/A
LGA Pad Offset (Land) :	eee	0.050
Ball Offset (Ball) :	fff	N/A
LGA Pad Count :	n	144
Edge LGA Pad Center to Center :	X	E1 13.970
	Y	D1 13.970
Center Pkg To Adjacent Center Of LGA Pad :	SE	0.635
	SD	0.635

TERMINAL DETAILS

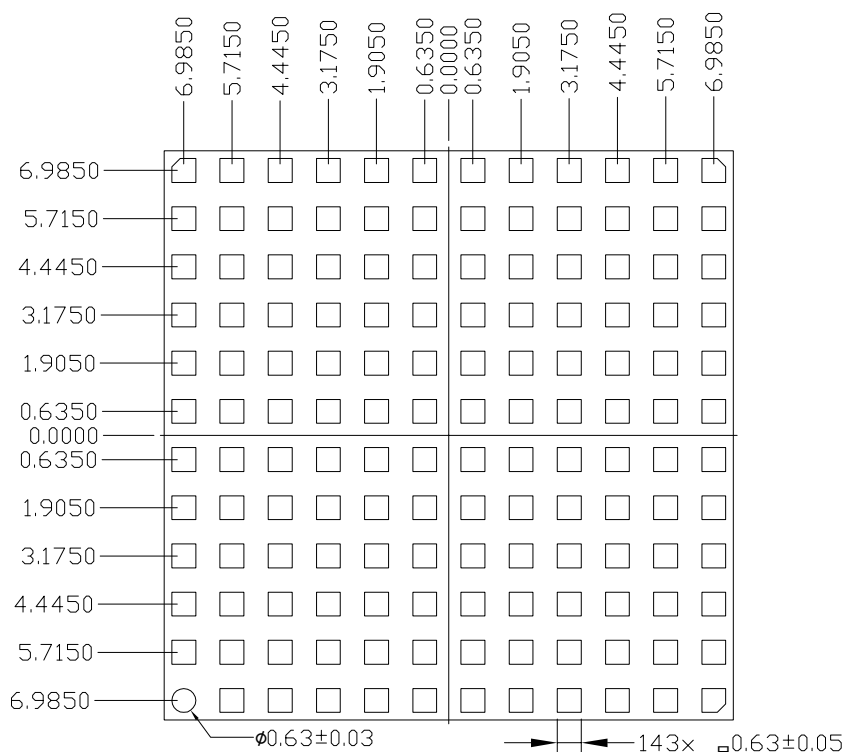


Suggested PCB Layout

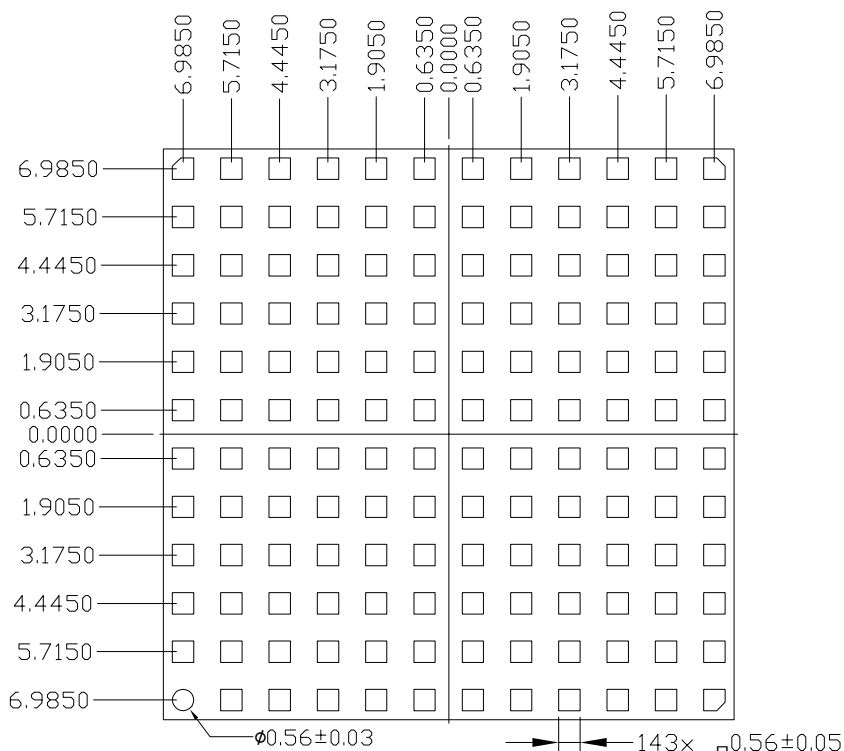
NOTE : ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES ARE IN DEGREES.

	MAXLINEAR CORPORATION	
	144LD 15x15x2.82mm SiPLGA Package Outline Drawing	
Packaging Approval:		Drawing No.: POD-0000089
By: YG Eom	Date: JAN.26.2018	Revision: A.1
		Sheet 1 OF 2

Revision History			
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TYPICAL RECOMMENDED LAND PATTERN



TYPICAL RECOMMENDED STENCIL

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		MAXLINEAR CORPORATION	
		144LD 15x15x2.82mm SiPLGA Package Outline Drawing	
Packaging Approval:		Drawing No.: POD-00000089	
By: YG Eom	Date: JAN.26.2018	Revision: A.1	Sheet 2 OF 2